

ABSTRACT

The present invention relates to a polishing head for pressing a polishing tape against a substrate, such as a wafer. The present invention further relates to a polishing apparatus for polishing a substrate with such a polishing head. The polishing head (10)
5 includes a pressing mechanism (12) configured to press a polishing tape (2) against a substrate W, and a tape hook (40) configured to restrict movement of an edge of the polishing tape (2) in a direction toward the substrate (W). The tape hook (40) has a tape positioning surface (47) that faces a polishing surface of the edge of the polishing tape (2).

FIG. 1